

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

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82 1 1. (Original): An image sensor comprising:  
2 a semiconductor substrate of a first conductivity type;  
3 a peripheral circuit formed on a first region of the semiconductor substrate,  
4 wherein a ground voltage level is applied to the first region;  
5 a unit pixel array having a plurality of unit pixels formed on a second region of  
6 the semiconductor substrate, wherein the first region is isolated from the second region and  
7 wherein a negative voltage level is applied to the second region; and  
8 a negative voltage circuit configured to provide the negative voltage for the  
9 second region.

1 2. (Original): The image sensor as recited in claim 1, wherein the image  
2 sensor comprises a buried layer isolating each of the unit pixels so that the buried layer surrounds  
3 the unit pixels.

1 3. (Original): The image sensor as recited in claim 2, wherein the  
2 semiconductor substrate comprises a P+-type substrate and a P-type epitaxial layer which is  
3 formed on the P+-type substrate, wherein the buried layer is formed in the P-type epitaxial layer.

1 4. (Original): The image sensor as recited in claim 3, wherein the negative  
2 voltage circuit comprises a P+ diffusion layer which is formed in the P-type epitaxial layer and  
3 wherein the negative voltage is applied to the P+ diffusion layer.

1 5. (Original): The image sensor as recited in claim 4, wherein the P+  
2 diffusion layer is shared with the second region of neighboring pixels.

1                   6.       (Original): An image sensor, comprising:  
2                   a plurality of unit pixels formed in a first region of a substrate that is biased at a  
3 ground reference, each pixel surrounded by a first epitaxial layer that is biased at a negative  
4 potential relative to the ground reference; and  
5                   a bias generator formed in a second region of the substrate that is biased to the  
6 ground reference.

7 - 14. (Canceled).

1                   15.       (Currently amended): A method of improving the charge transfer  
2 efficiency of a photodiode device, the method comprising the steps of:  
3                   providing a ground reference in a first region formed in a substrate;  
4                   providing a bias generator in the first region for generating a negative potential  
5 relative to the ground reference; and  
6                   providing a photodiode device in a second region formed in the substrate  
7 including spacing apart the first region and the second region and isolating the second region  
8 from the first region, the photodiode device having a photodiode including a p-type side that is  
9 electrically coupled to the negative potential.

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